

# **Shri G. S. Institute of Technology and Science**

## **Department of Electronics and Instrumentation Engineering**

### **Four Week Internship**

### **on**

### **Analog Chip Design**



**Celebrating 72 Year**

**PRESENTED BY**

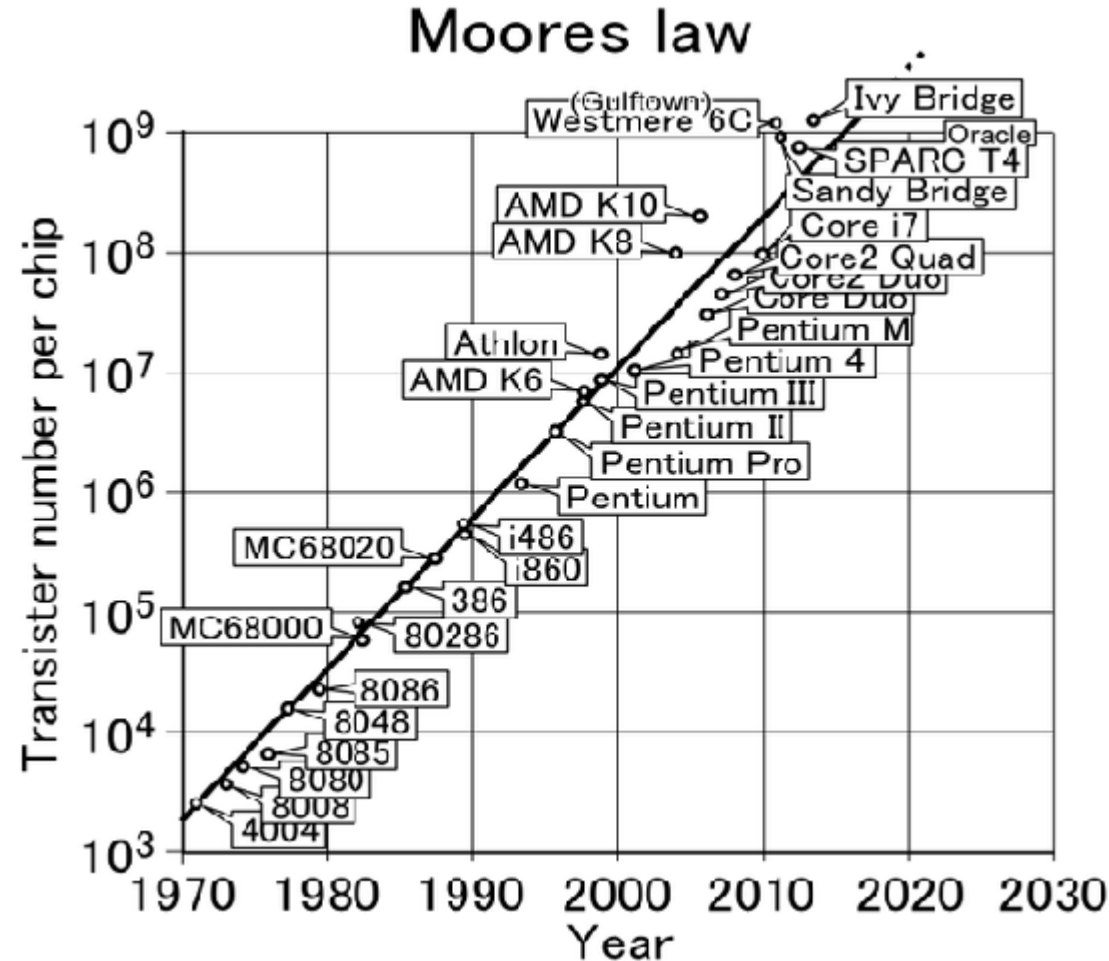
**Dr. Rajesh Khatri (Associate Professor)**

# Analog Chip Design

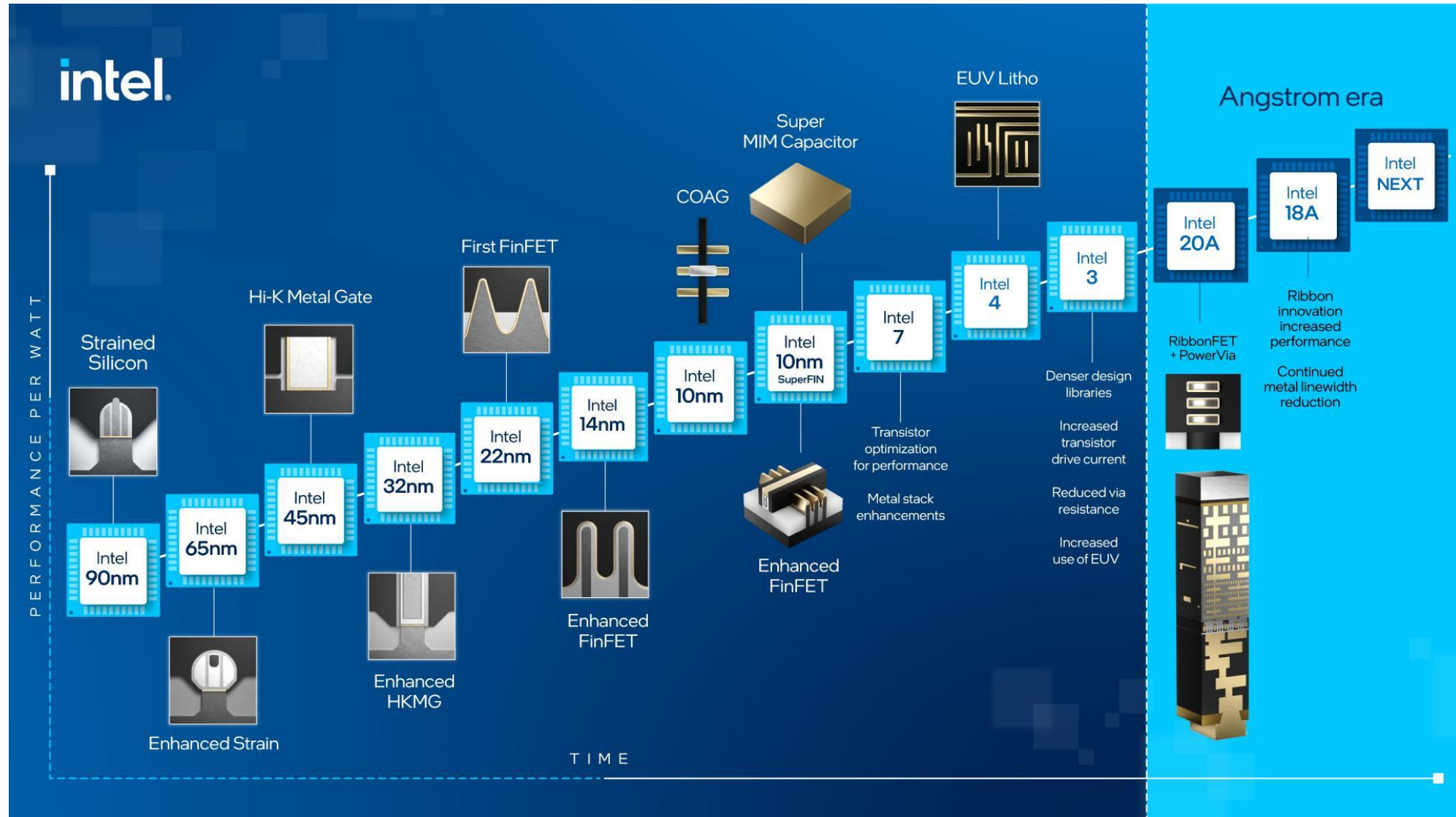
- What is VLSI?
  - Very Large-Scale Integration
  - Integration of gates or transistors?
- SSI – Small Scale Integration ( $0-10^2$ )
- MSI – Medium Scale Integration ( $10^2-10^3$ )
- LSI – Large Scale Integration ( $10^3-10^5$ )
- VLSI – Very Large-Scale Integration ( $\geq 10^7$ )

# Analog Chip Design

## ➤ Moore's Law



# Analog Chip Design



# Analog Chip Design

➤ How to integrate millions and billions transistor?

➤ Solution-

EDA Tools / CAD Tools

Electronic Design Automation Tools

➤ Cadence

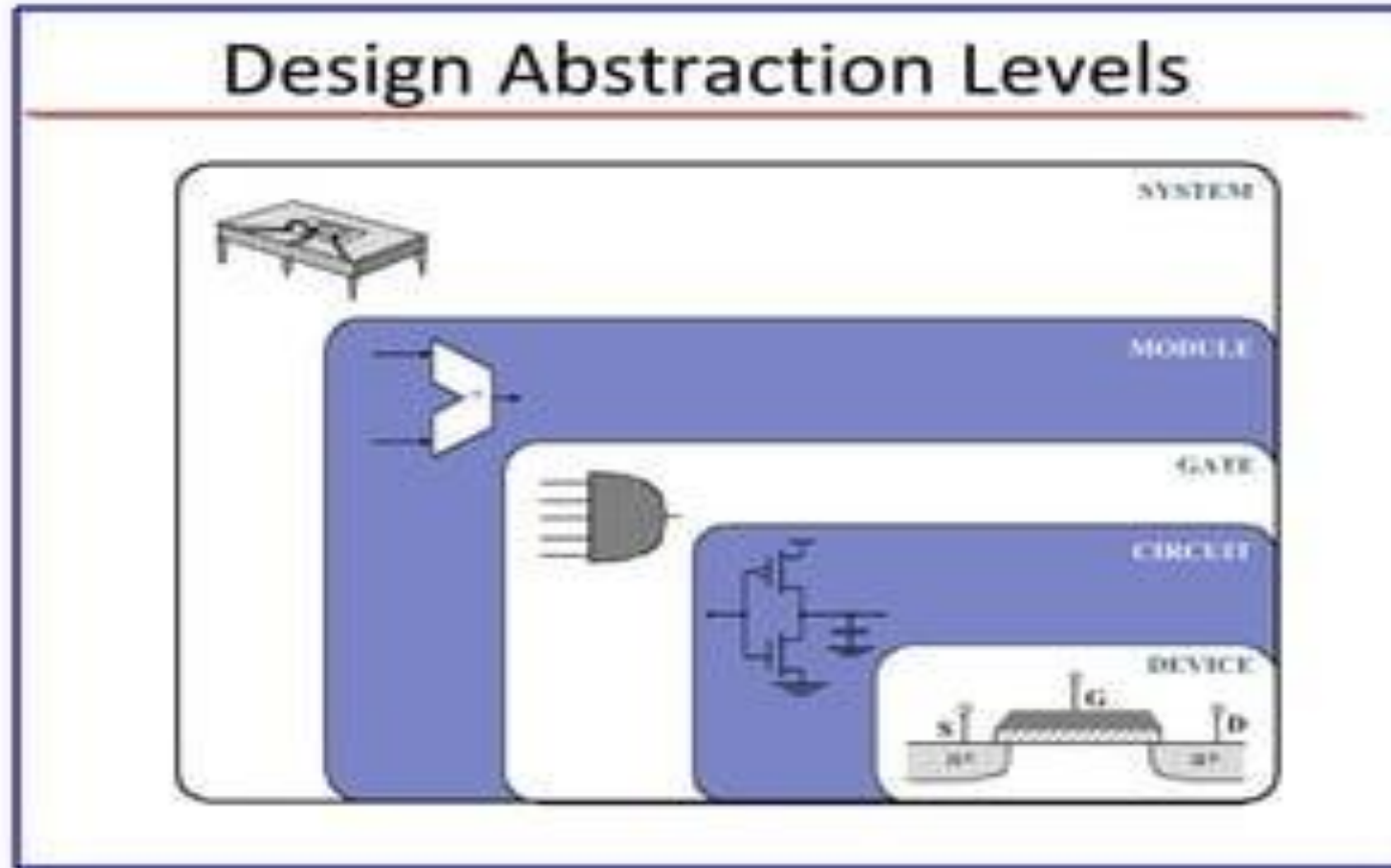
➤ Synopsys

➤ Mentor Graphics (Siemens)

# Analog Chip Design

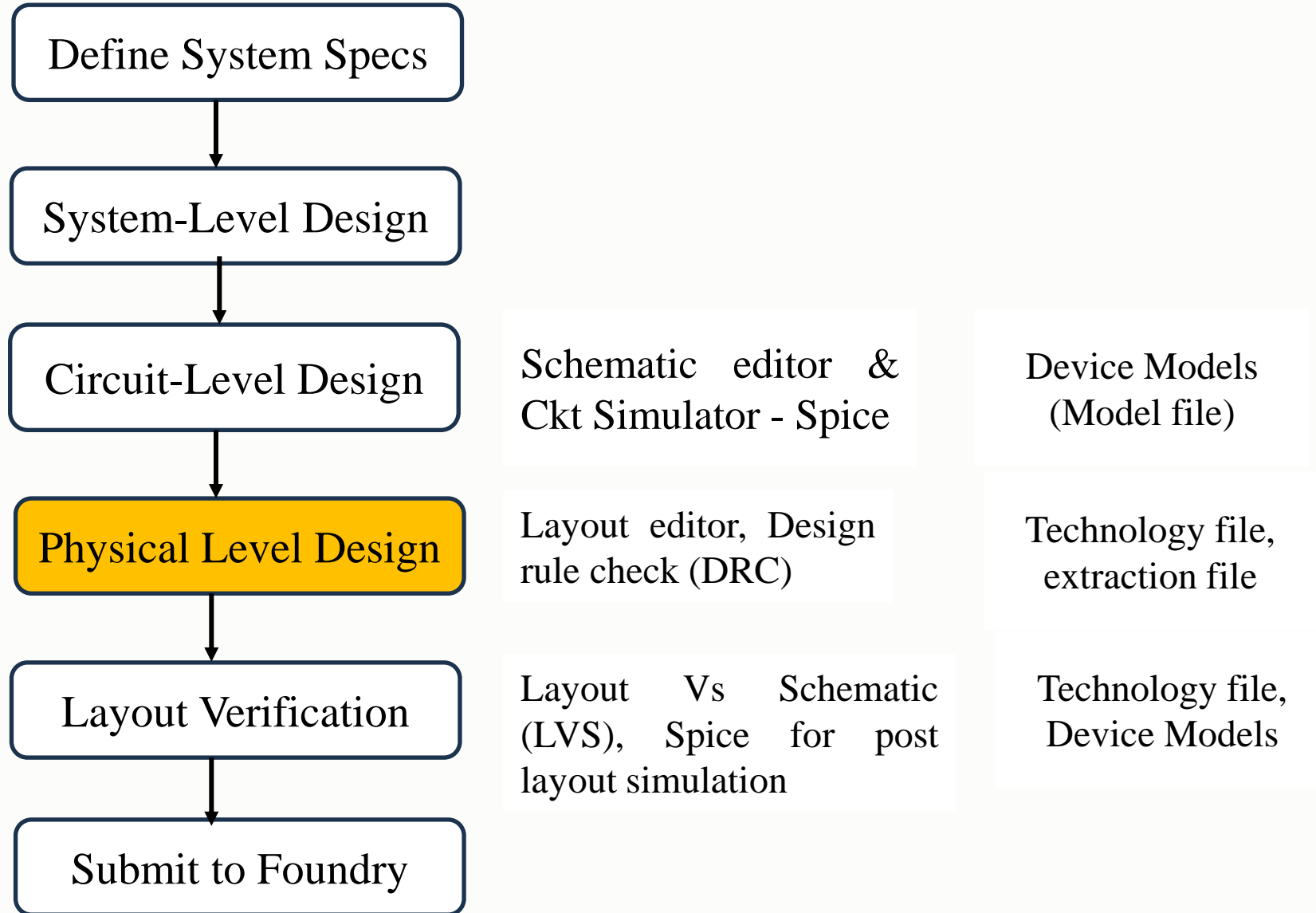
- Front end and Back end
- Front end: initial conceptualization, system level description, architecture level, RTL coding
- Back end: Physical implementation, floor planning placement and routing

# Analog Chip Design



# Chip Design Flow Using Cadence

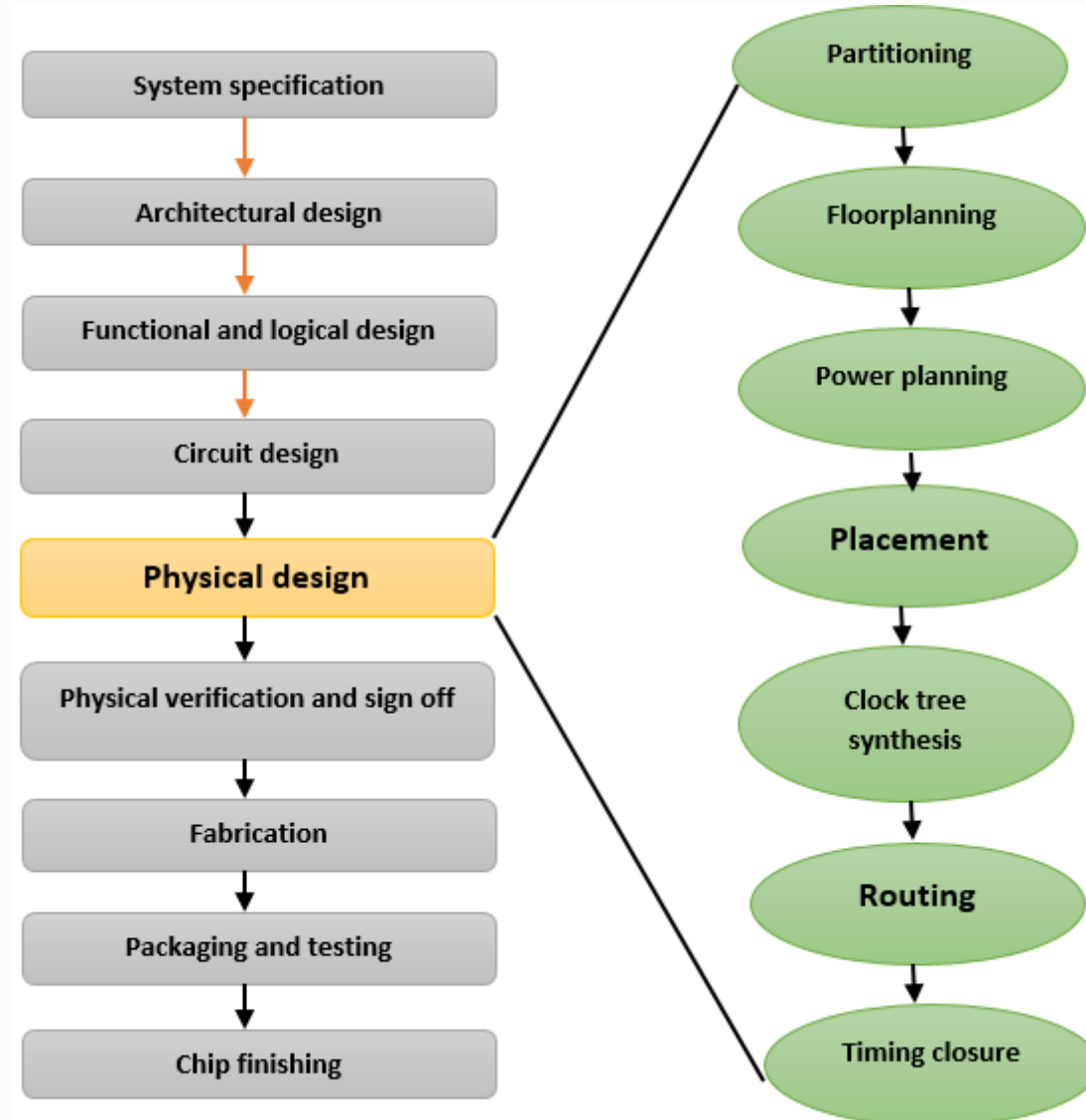
- Chip Design Flow





# Chip Design Flow Using Cadence

## Chip Design Flow



# Chip Design Flow Using Cadence



- **Model File:**
- **Technology File:** The technology file provides information on various aspects, including layer definitions, design rules, spacing requirements, wire widths, and other parameters that guide the layout of the integrated circuit.
- **PDK (Process Design Kit) :** It's a set of libraries and associated data (model files, physical verification rule files, control files for various tools) to allow you to design in a particular technology.

# Chip Design Flow Using Cadence

- PDK's : Vendors – gpdk- Generic PDK

SCL (Semi-conductor Laboratory)

UMC – (United Microelectronics Corporation)

TSMC – (Taiwan Semiconductor Manufacturing Company)

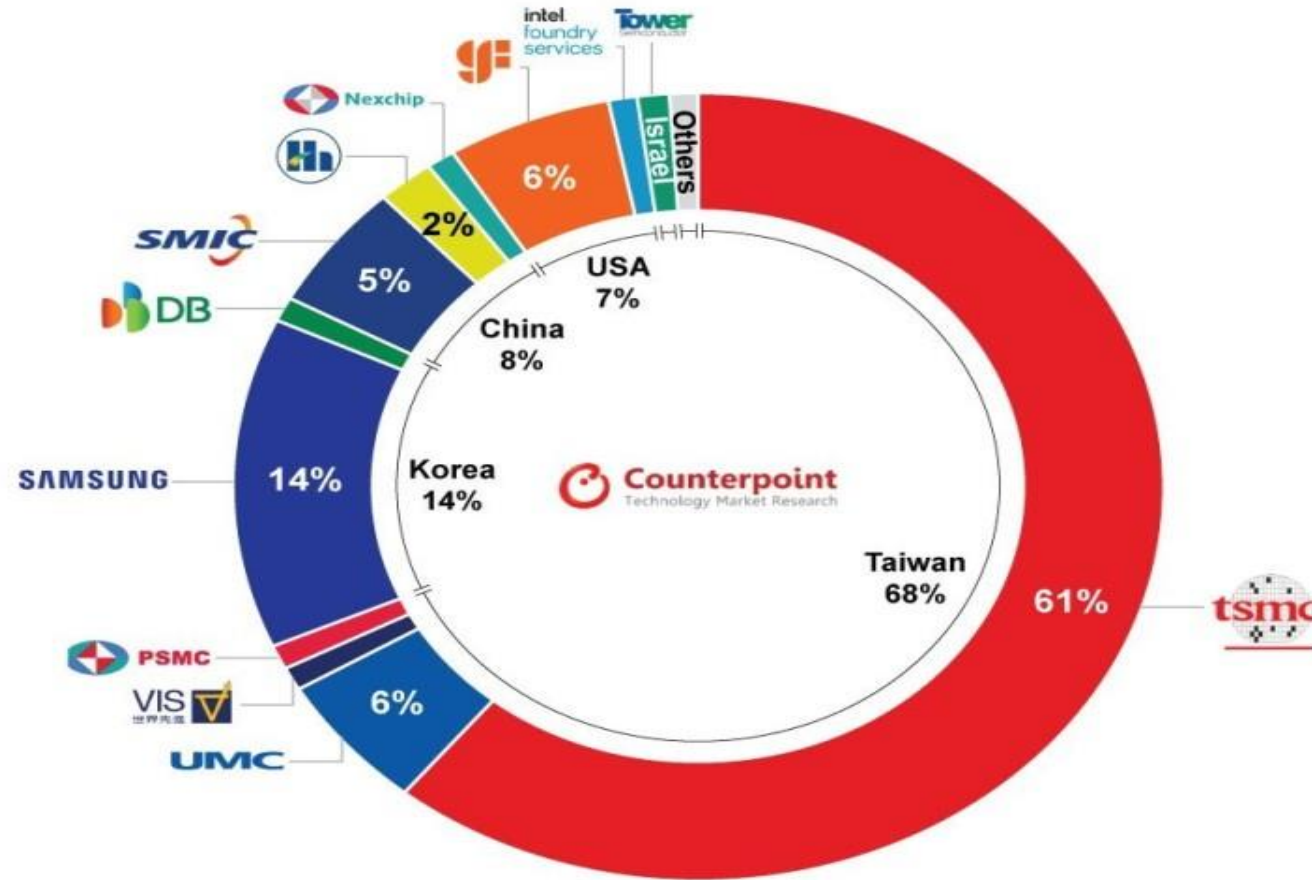
Tower Semiconductor

Global Foundries

SMIC – (Semiconductor Manufacturing International Corporation)

# Chip Design Flow Using Cadence

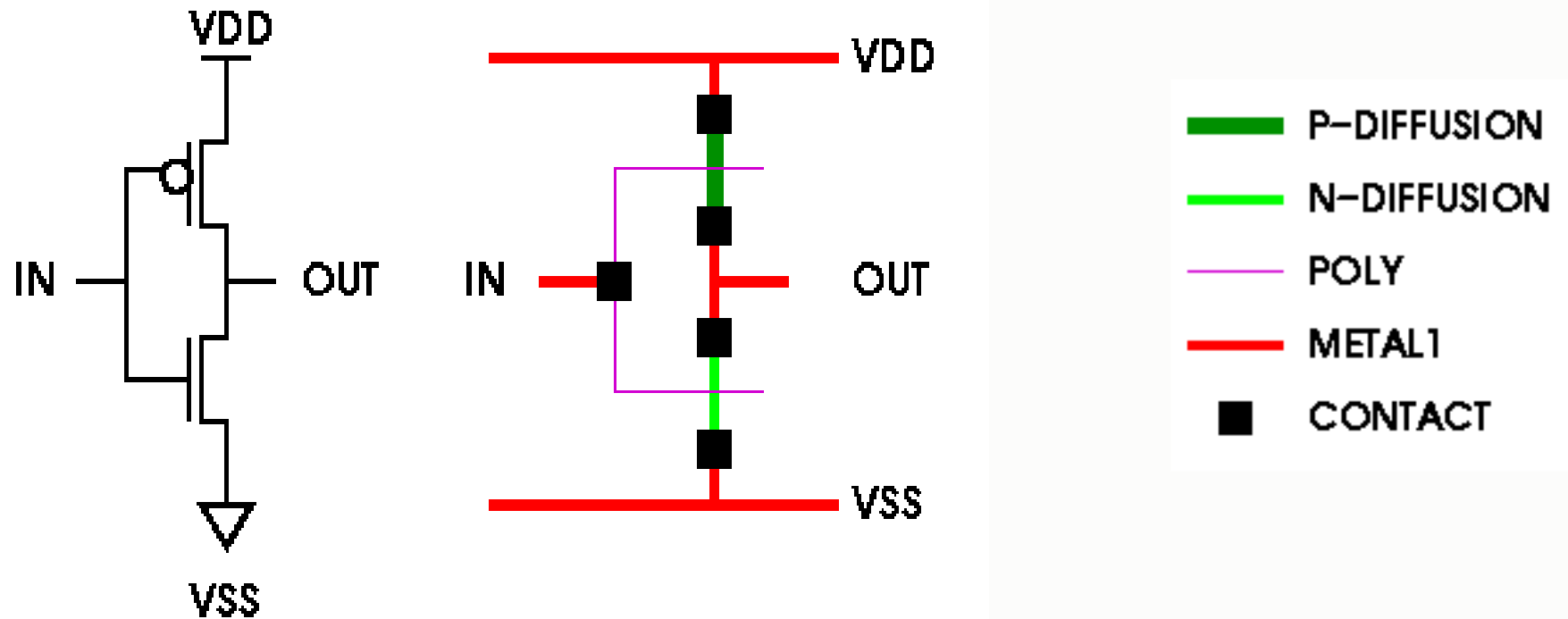
**Revenue Share of Key Players in Global Semiconductor Foundry Industry, Q4 2023**



Source: Counterpoint Foundry Revenues Tracker

# Chip Design Flow Using Cadence

## ✓ CMOS Inverter and Stick Diagram



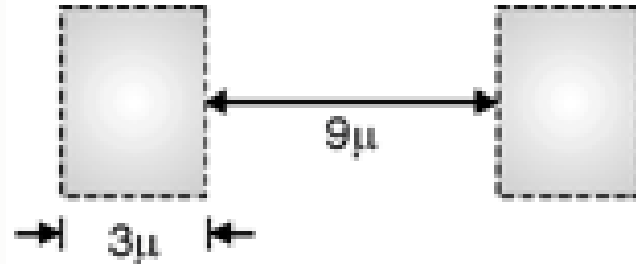
# Chip Design Flow Using Cadence

- Layout Design Rules
  - Lambda Based Design Rules
  - Micron based Design Rules
- Lambda Based Design Rules
  - Expressed in terms of a scaling parameter: Lambda ( $\lambda$ )
  - Minimum line width:  $2\lambda$
  - Main disadvantages:
    - Limited linear scaling
    - Too conservative

# Chip Design Flow Using Cadence

- Micron Based Design Rules
  - Express designs in absolute dimensions
  - Pro: Allow taking full advantage of technology
  - Con: Scaling and Porting becomes more complicated
- (1) Rules for N-well as shown in Figure below.

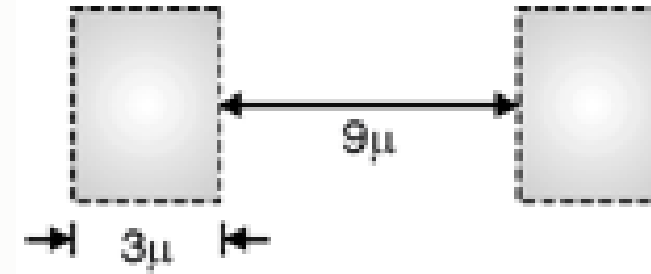
- Width  $3\mu$
- Space  $9\mu$



# Chip Design Flow Using Cadence

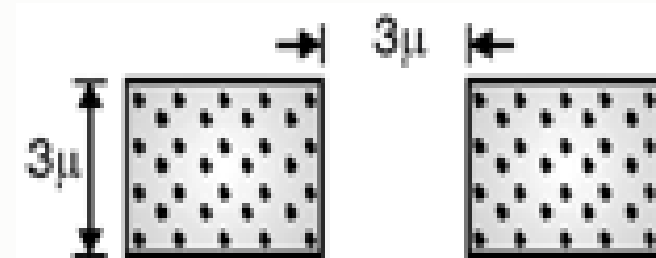
## • 2) Rules for active area as shown in Figure below

- 1. Minimum size =  $3\mu$
- 2. Minimum spacing =  $3\mu$
- 2. N+ active to N-well =  $7\mu$



## (3) Rules for poly 1 as shown in Figure below.

1. Width =  $2\mu$
2. Spacing =  $3\mu$
3. Gate overlap of active =  $2\mu$
4. Field poly 1 to active =  $1\mu$

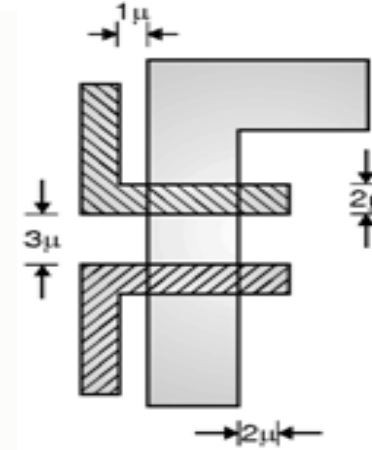




# Chip Design Flow Using Cadence

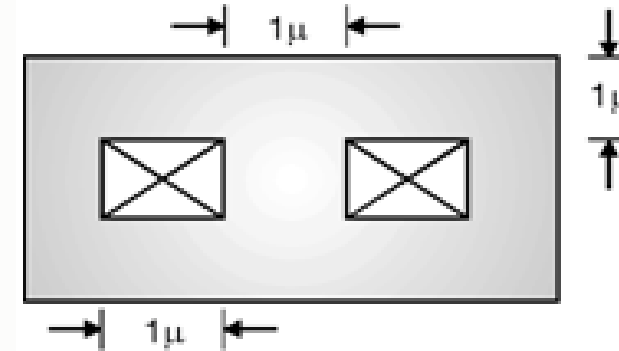
## • 4) Rules for contact to Poly as shown in Figure below

- 1. Exact contact size =  $2\mu \times 2\mu$
- 2. Minimum Poly overlap =  $1\mu$
- 3. Minimum contact spacing =  $2\mu$



## • (5) Rules for contact to Active as shown in Figure below.

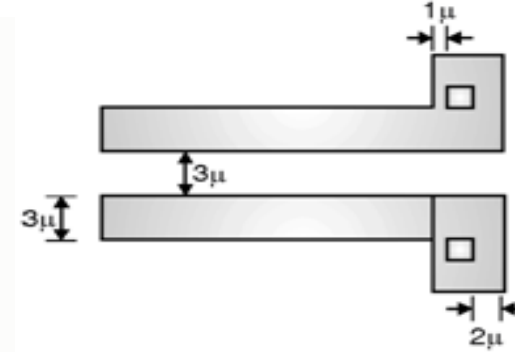
1. Exact contact size =  $2\mu \times 2\mu$
2. Minimum active overlap =  $1\mu$
3. Minimum contact spacing =  $2\mu$
4. Minimum spacing to gate =  $2\mu$



# Chip Design Flow Using Cadence

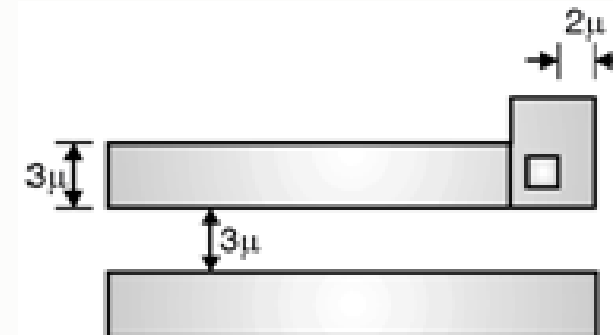
- 6) Rules for Metal 1 as shown in Figure below

- 1. Width =  $3\mu$
- 2. Spacing =  $3\mu$
- 3. Overlap of contact =  $1\mu$

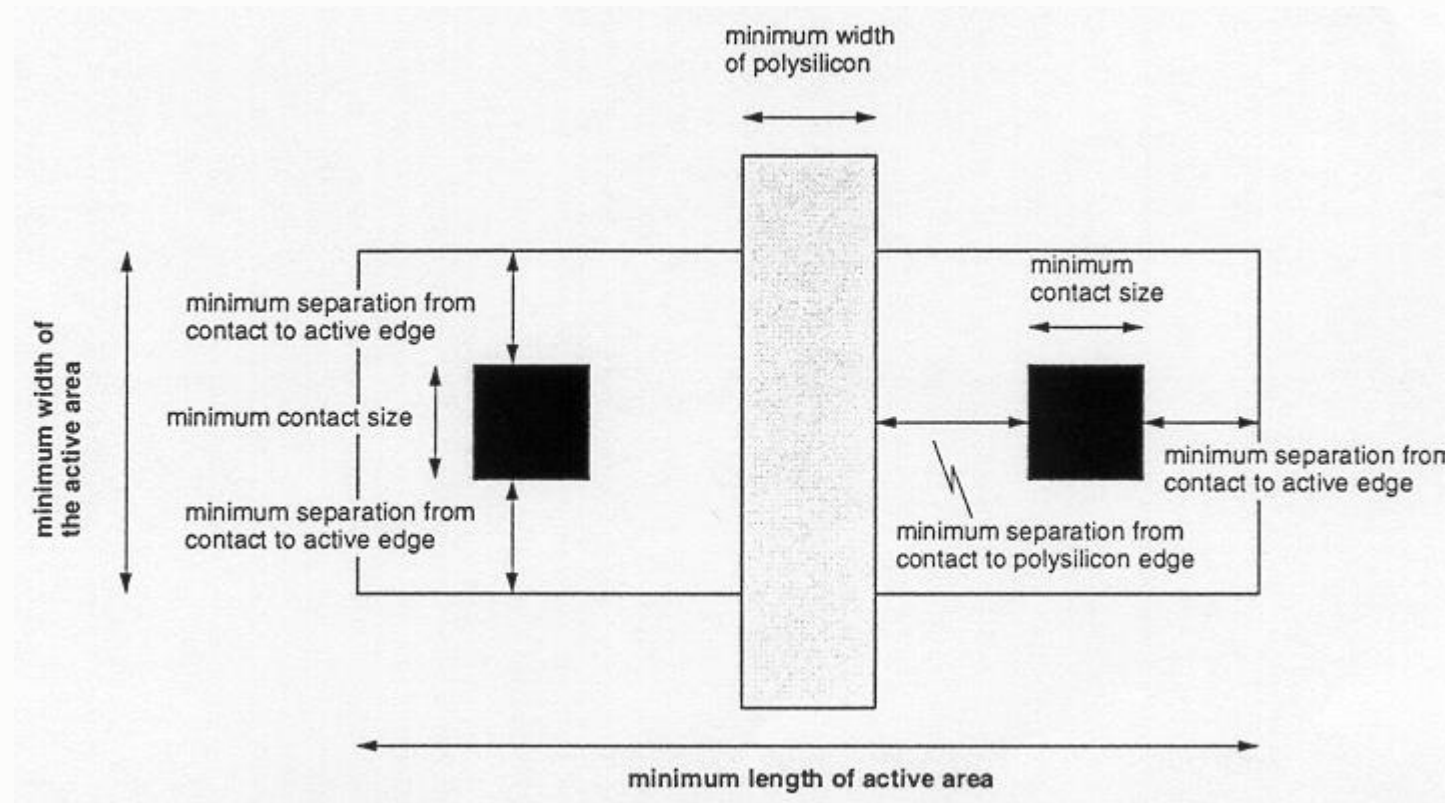


- (7) Rules for Metal 2 as shown in Figure below.

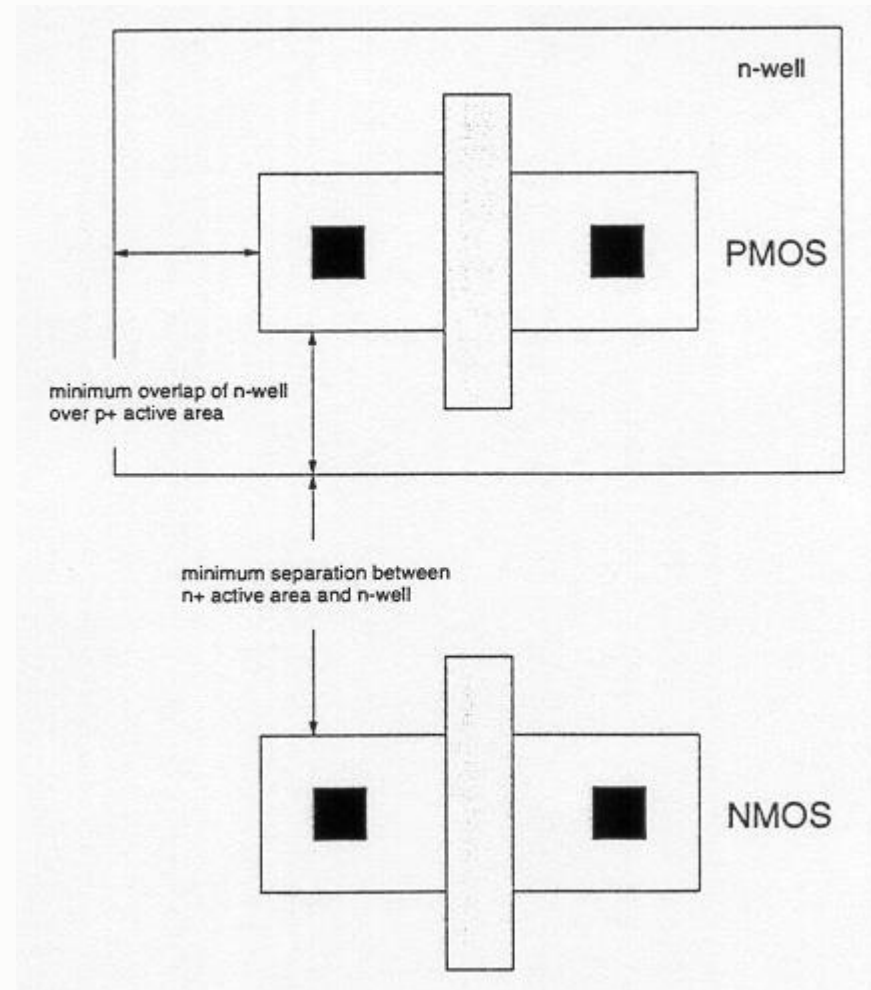
- 1. Width =  $3\mu$
- 2. Spacing =  $3\mu$
- 3. Overlap of contact =  $1\mu$



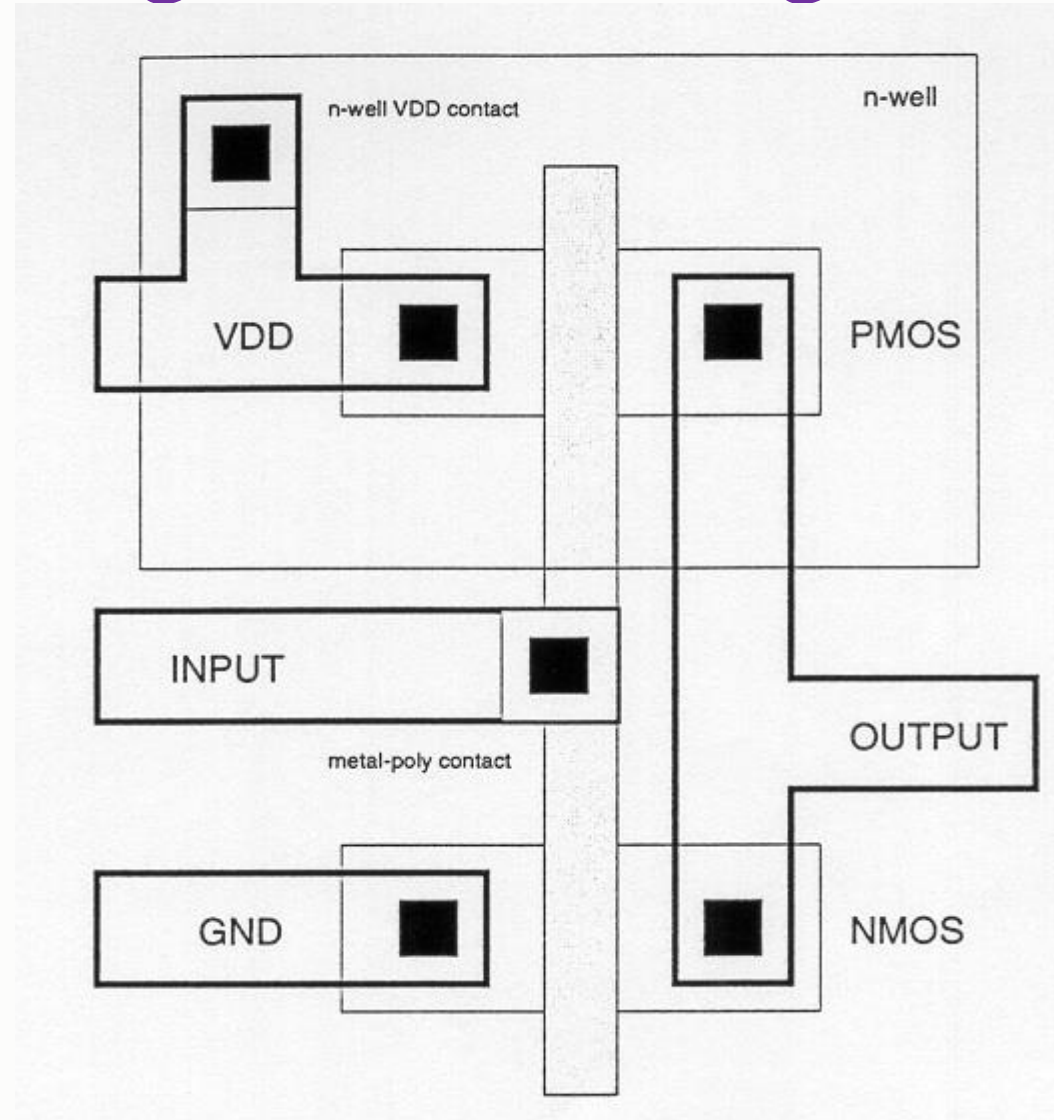
# Chip Design Flow Using Cadence



# Chip Design Flow Using Cadence

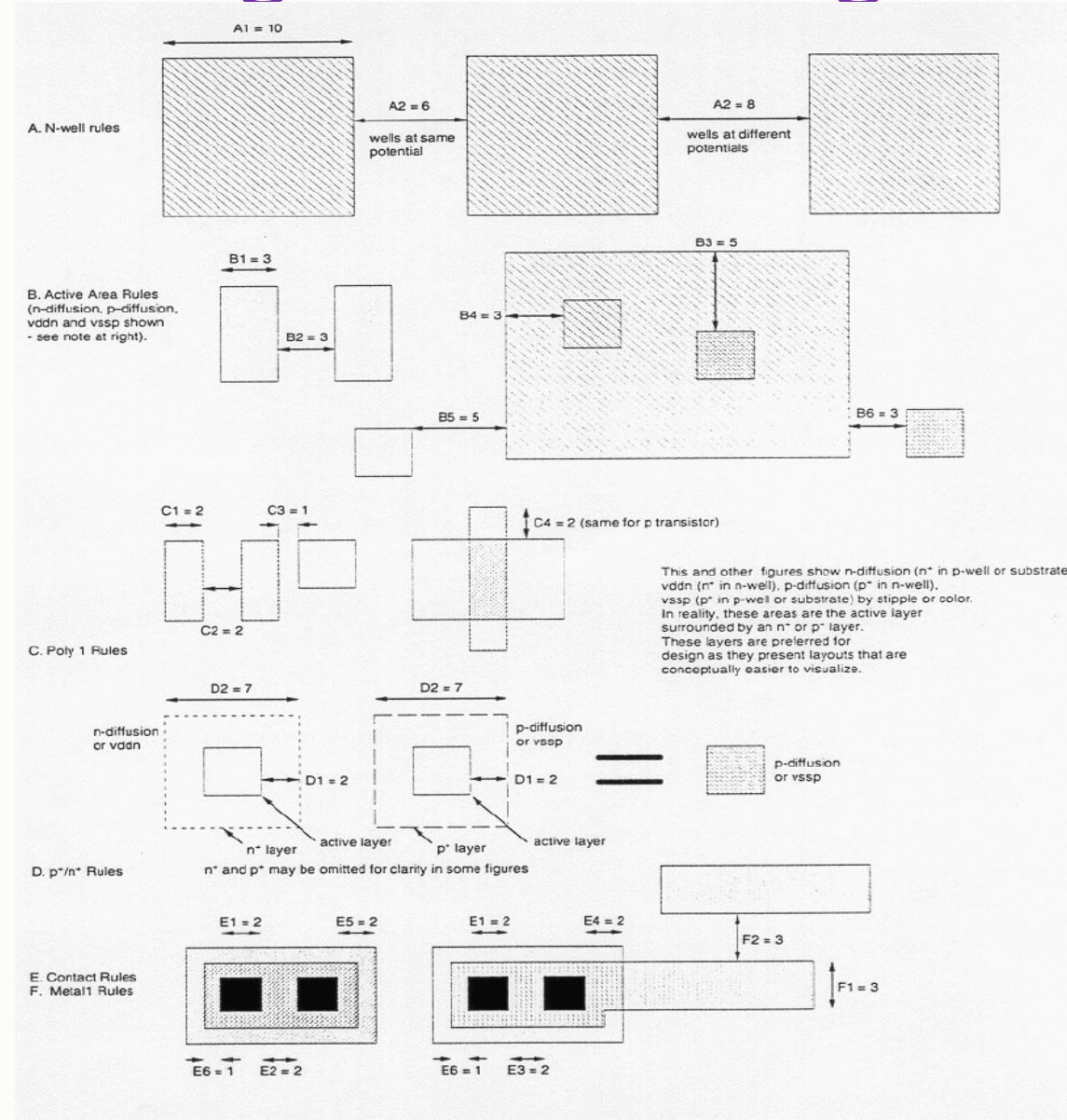


# Chip Design Flow Using Cadence

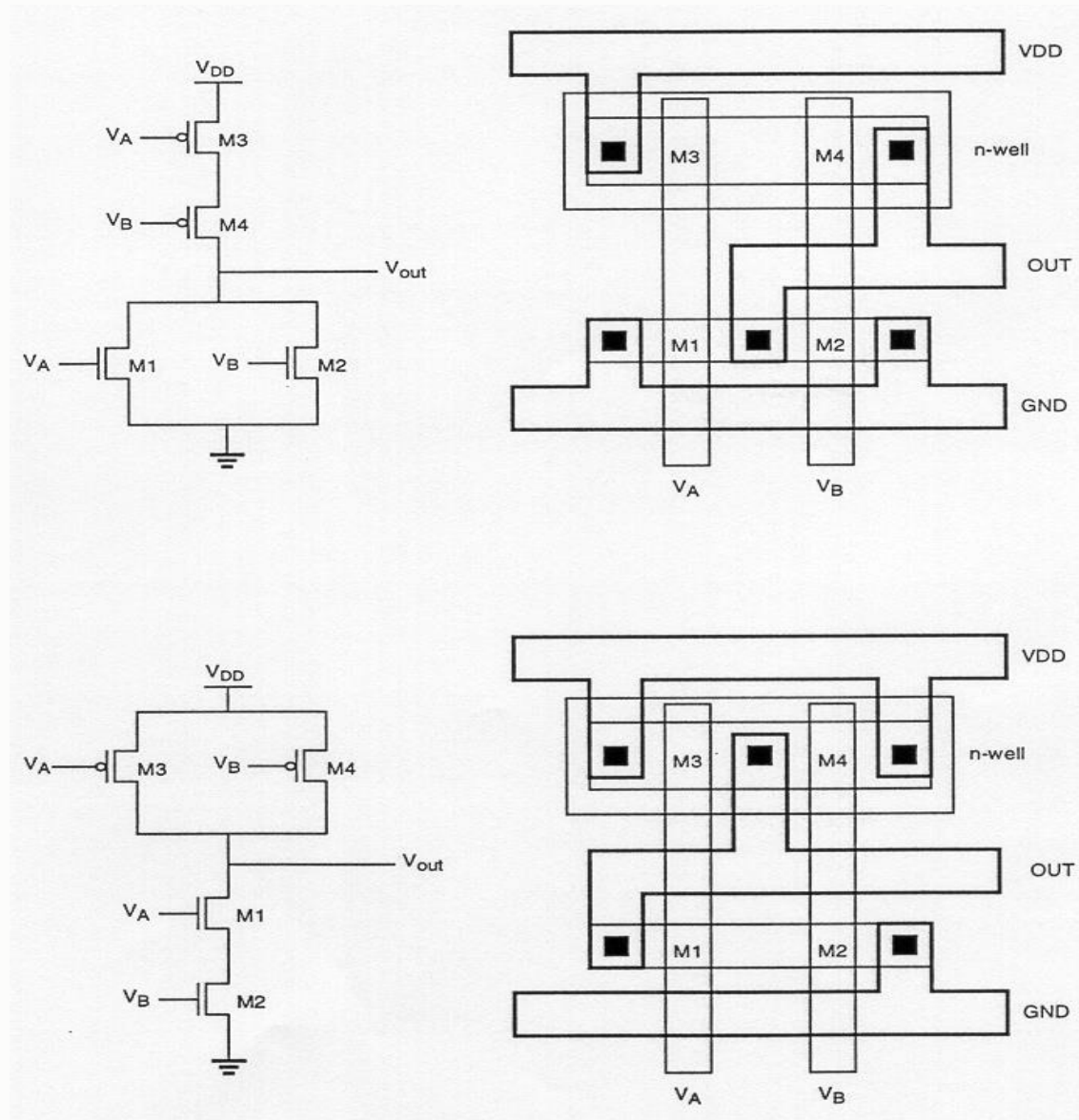




# Chip Design Flow Using Cadence

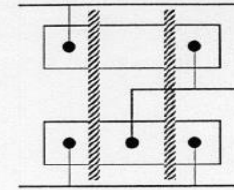


# Chip Design Flow Using Cadence

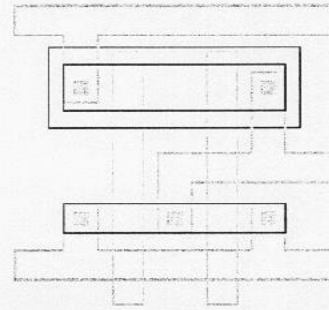


# Chip Design Flow Using Cadence

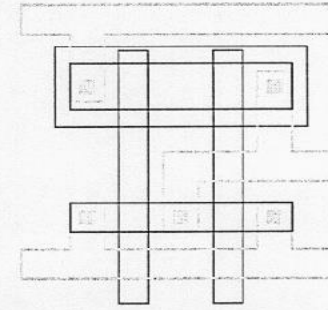
Mask layout of a CMOS NOR gate



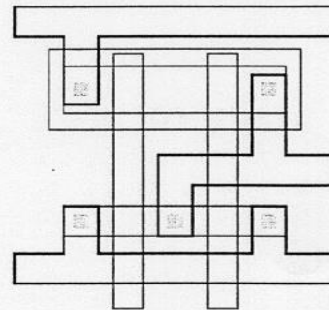
stick diagram layout



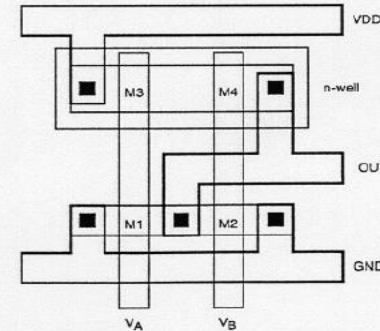
n-well and active area masks



poly mask -> define nMOS and pMOS transistors



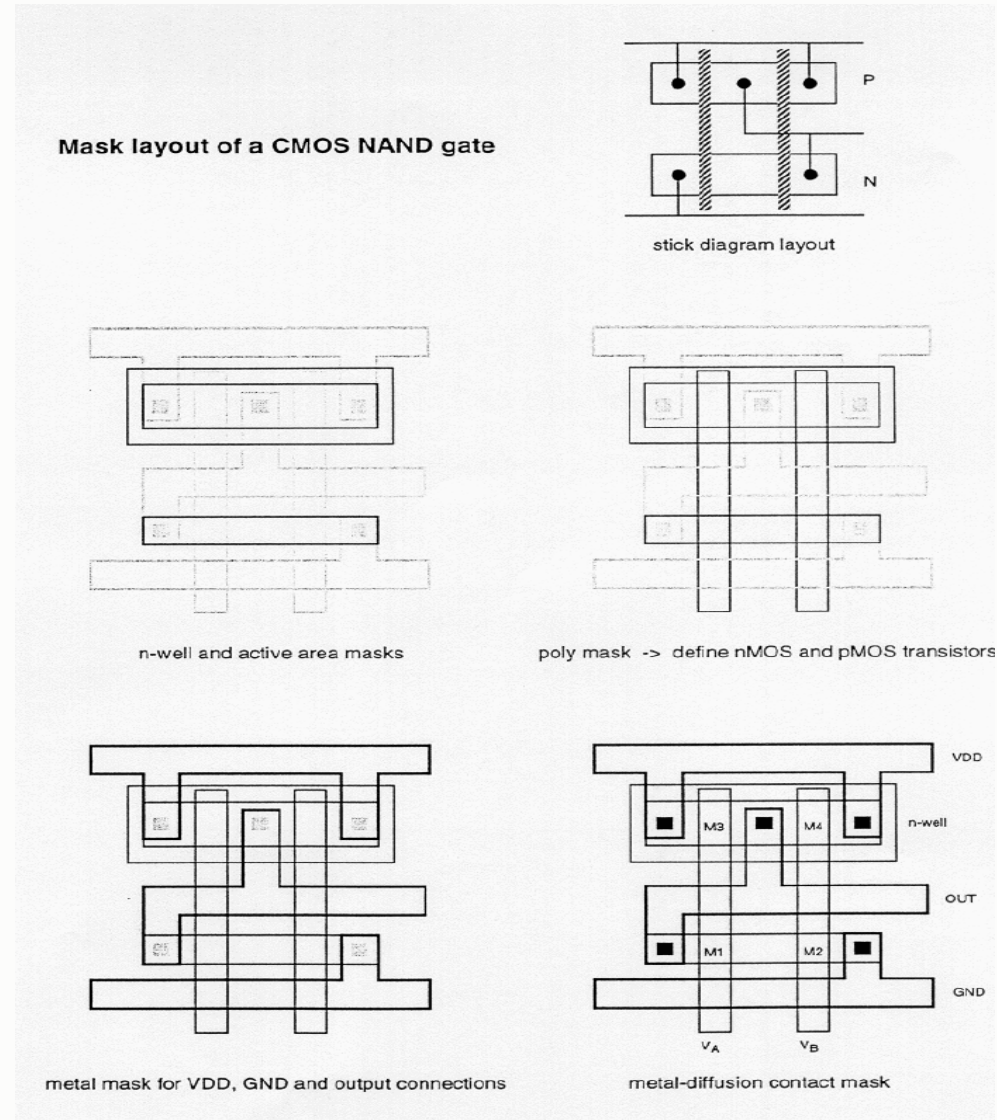
metal mask for VDD, GND and output connections



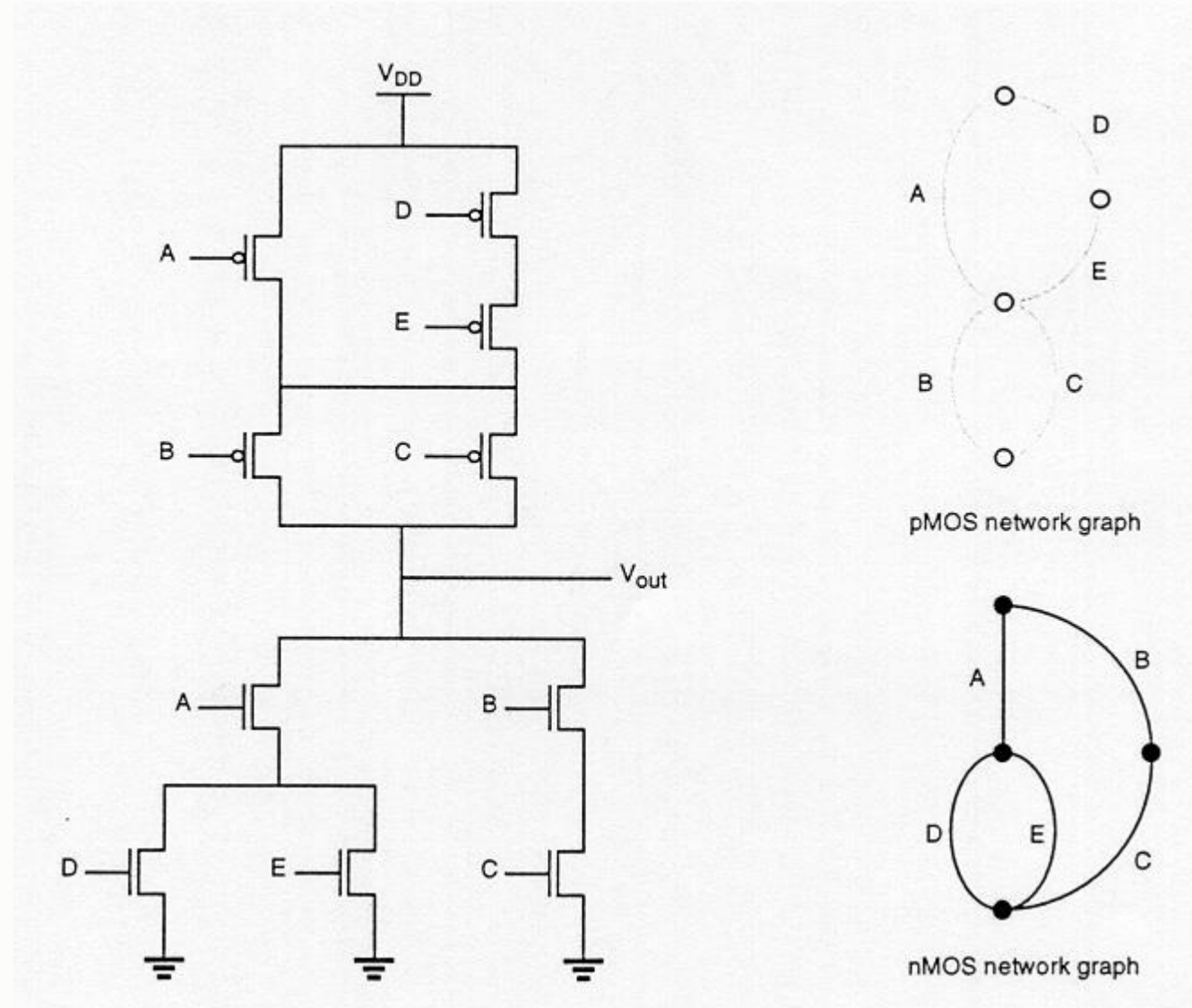
metal-diffusion contact mask



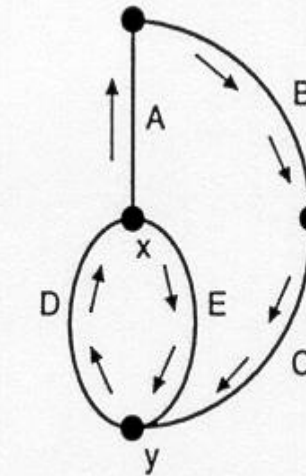
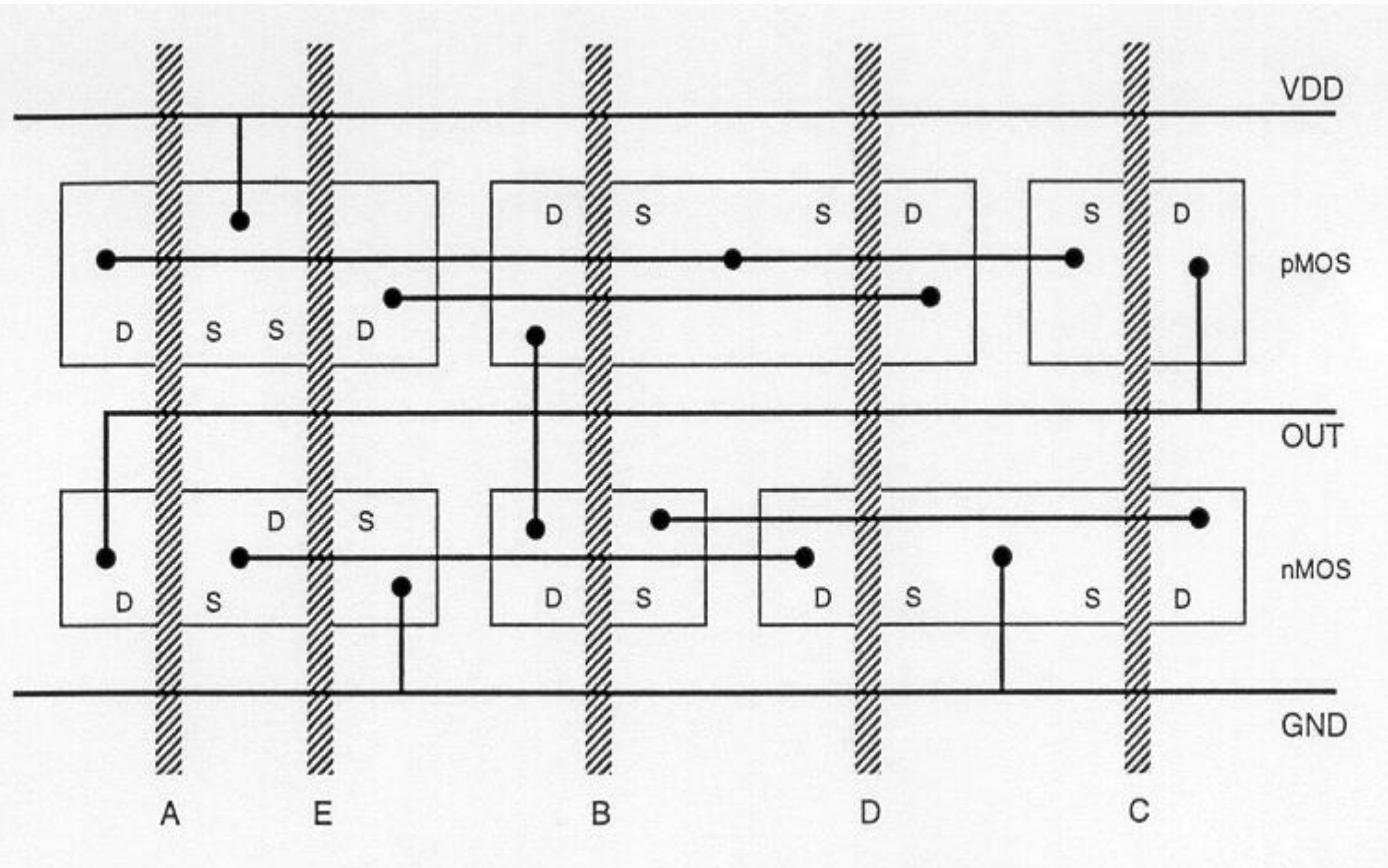
# Chip Design Flow Using Cadence



# Chip Design Flow Using Cadence

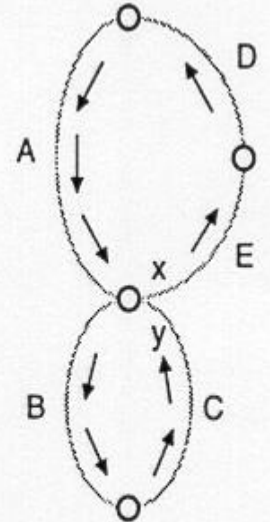


# Chip Design Flow Using Cadence



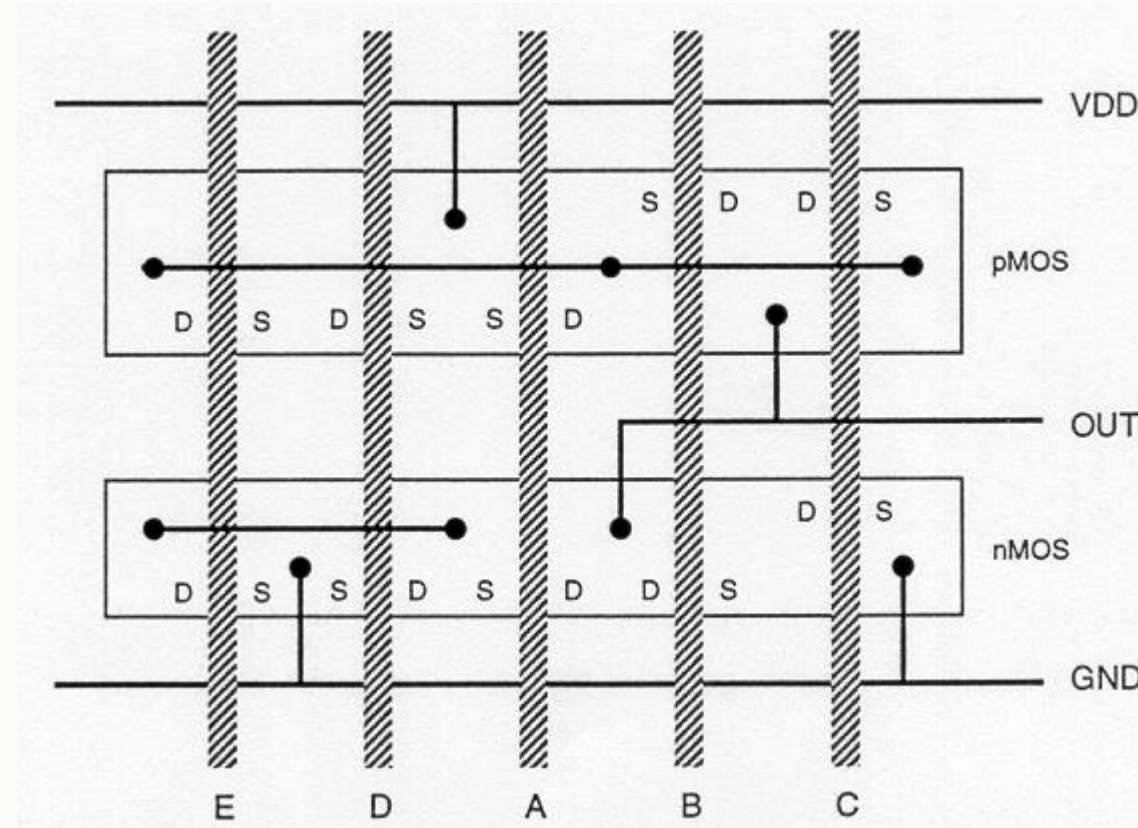
nMOS network graph

Common Euler path :  
E - D - A - B - C



pMOS network graph

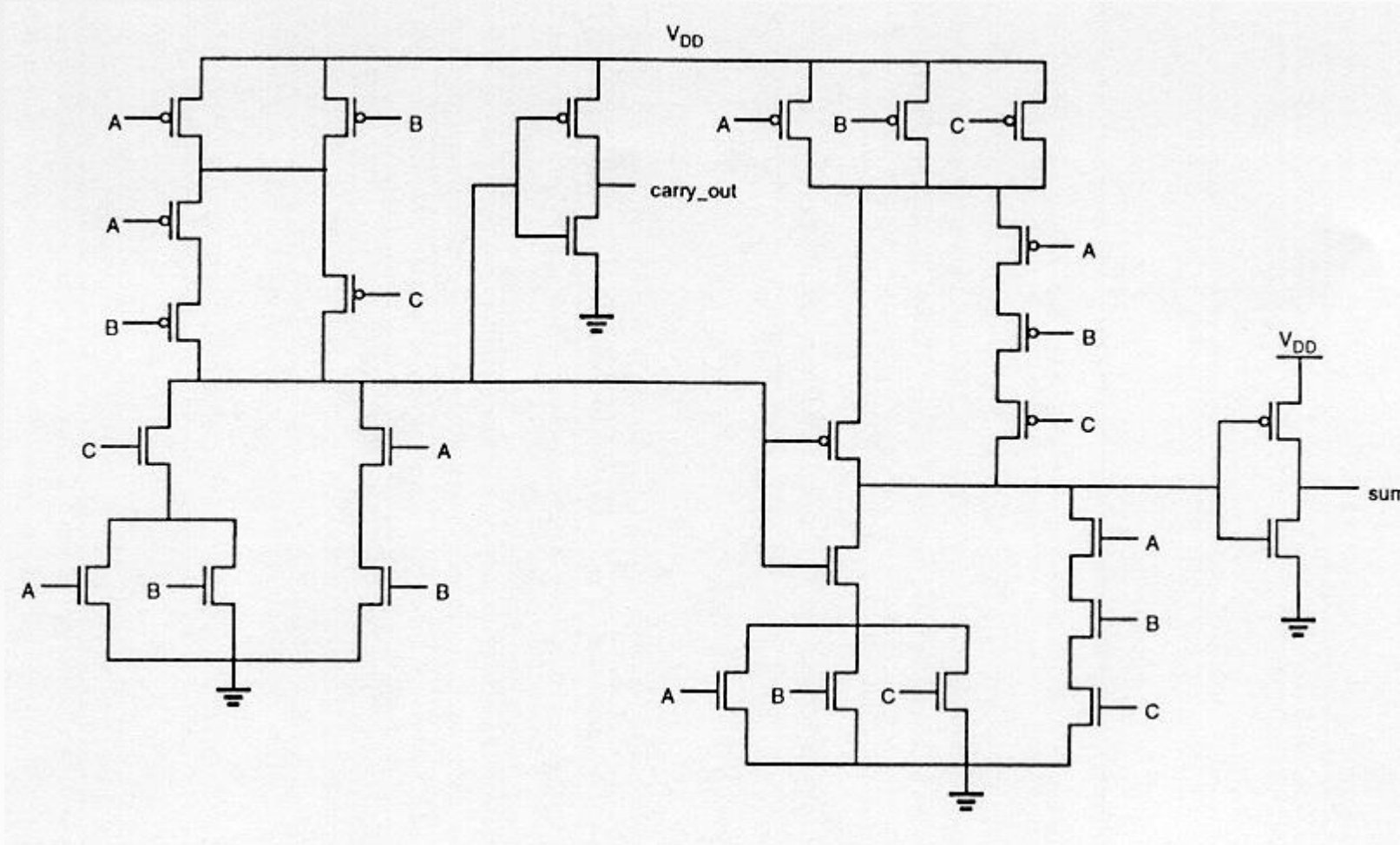
# Chip Design Flow Using Cadence





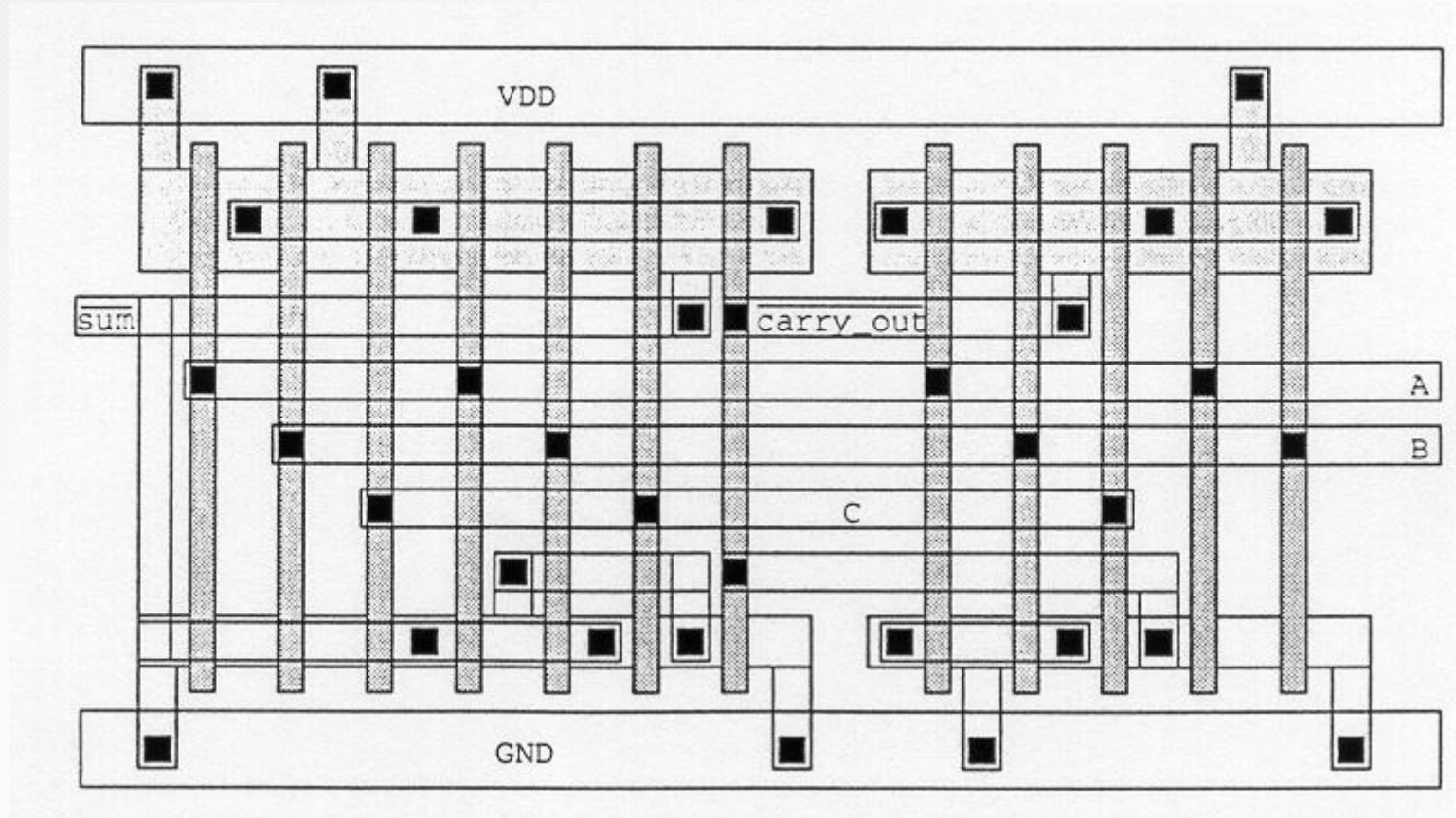
# Chip Design Flow Using Cadence

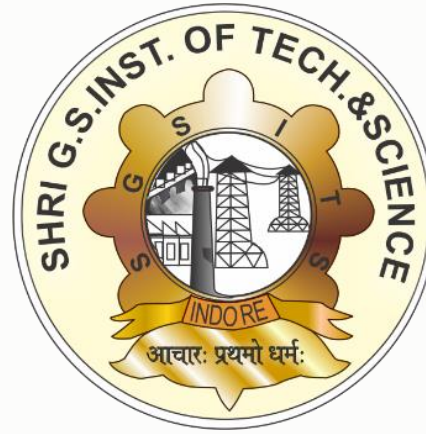
## ✓ Full Adder



# Chip Design Flow Using Cadence

## ✓ Full Adder Layout





# THANK YOU